

Electronic Patent Application Fee Transmittal

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|---|--|-----------------|---------------|-----------------------------|
| Application Number: | 10611334 | | | |
| Filing Date: | 30-Jun-2003 | | | |
| Title of Invention: | MEMS PACKAGING USING A NON-SILICON SUBSTRATE FOR ENCAPSULATION AND INTERCONNECTION | | | |
| First Named Inventor/Applicant Name: | John Heck | | | |
| Filer: | Kevin Reif/cathy dikes | | | |
| Attorney Docket Number: | 42P16325 | | | |
| Filed as Large Entity | | | | |
| Utility Filing Fees | | | | |
| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Utility Appl issue fee | 1501 | 1 | 1440 | 1440 |
| Publ. Fee- early, voluntary, or normal | 1504 | 1 | 300 | 300 |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|--------------------|----------|----------|--------|----------------------|
| Extension-of-Time: | | | | |
| Miscellaneous: | | | | |
| Total in USD (\$) | | | | 1740 |